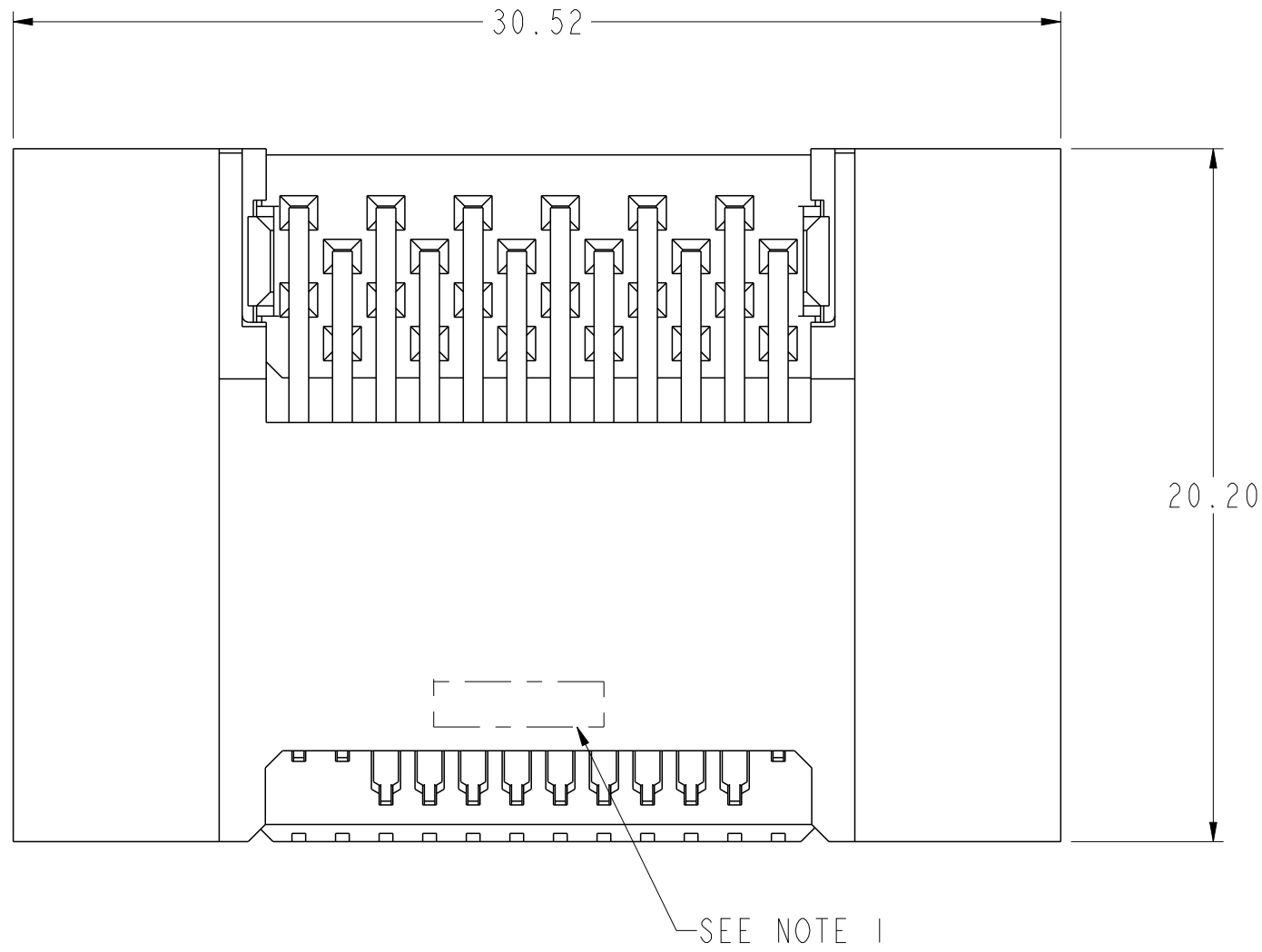
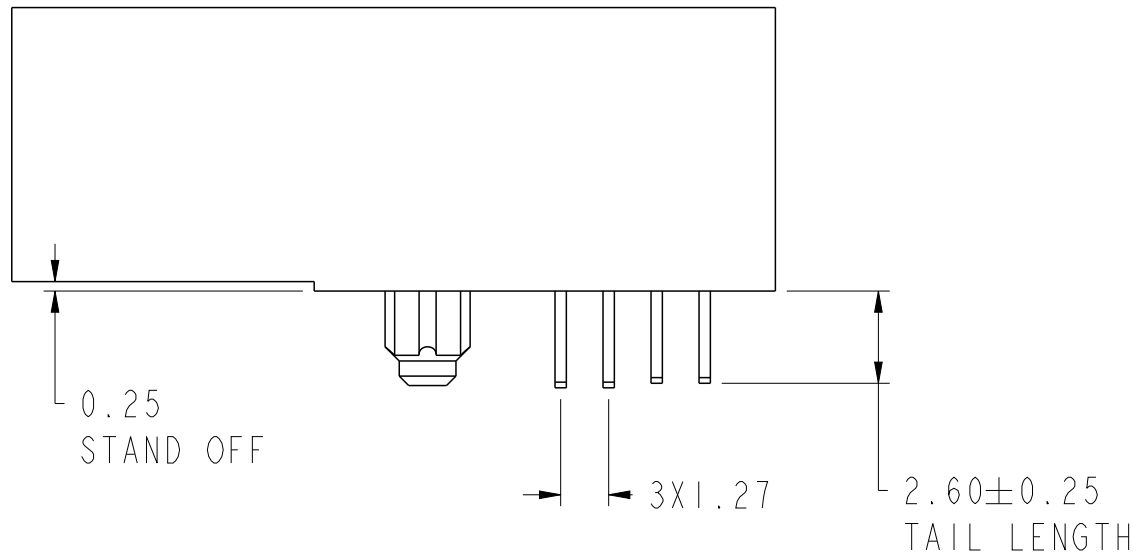
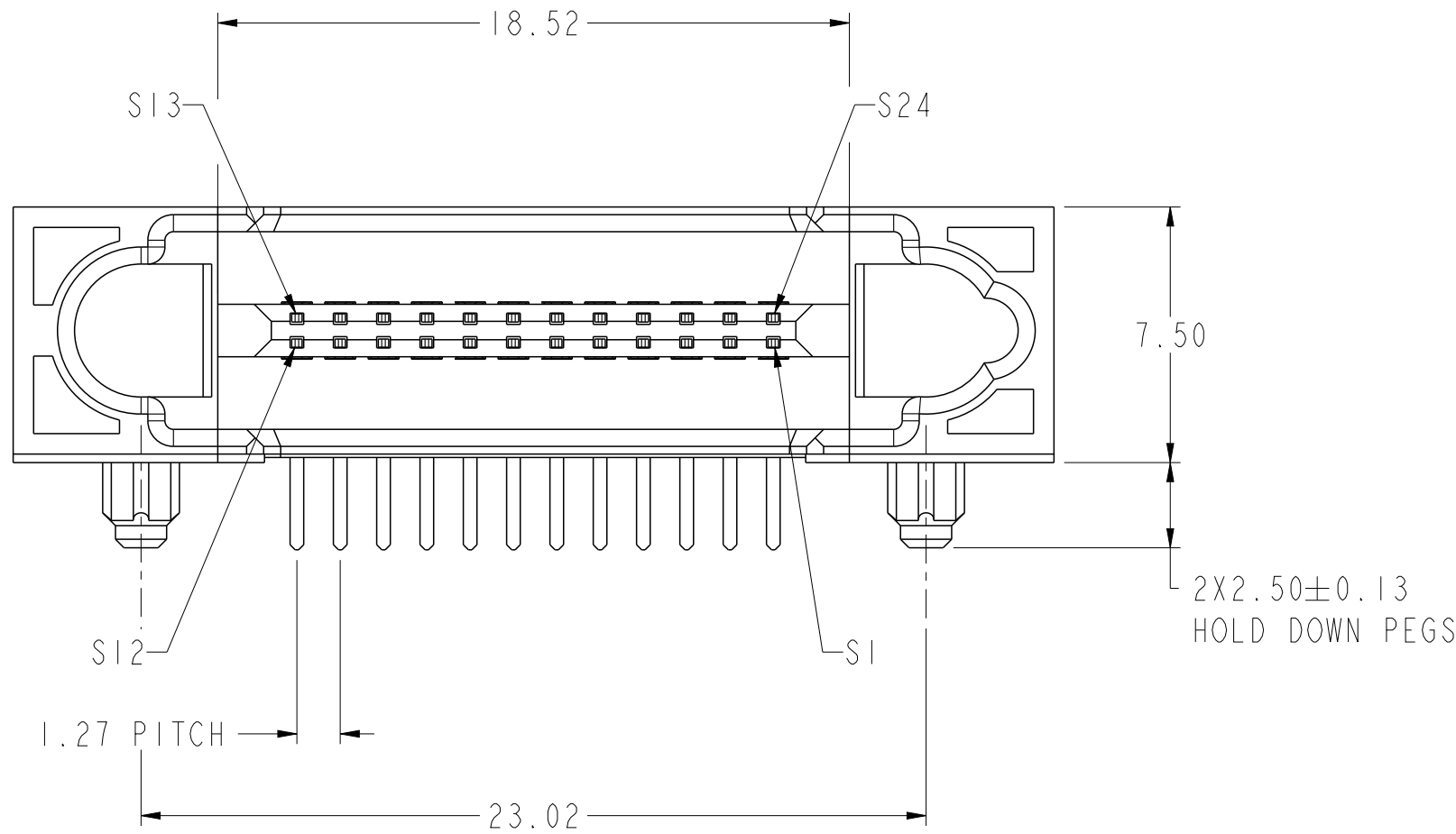




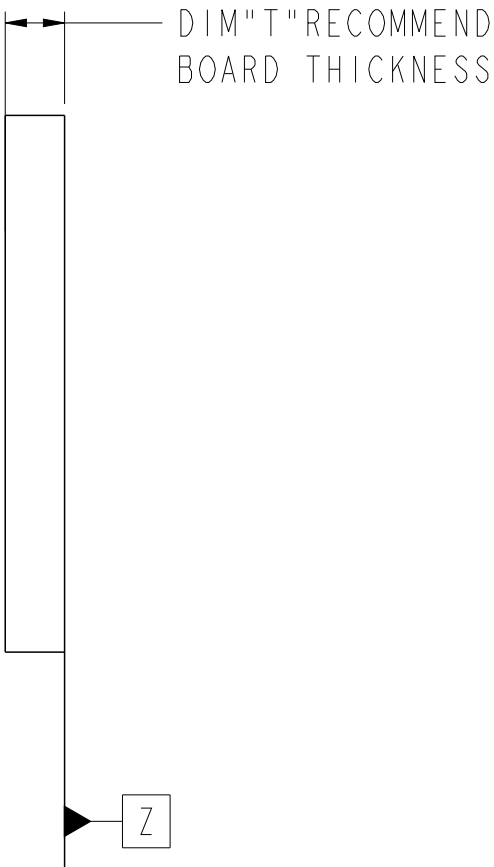
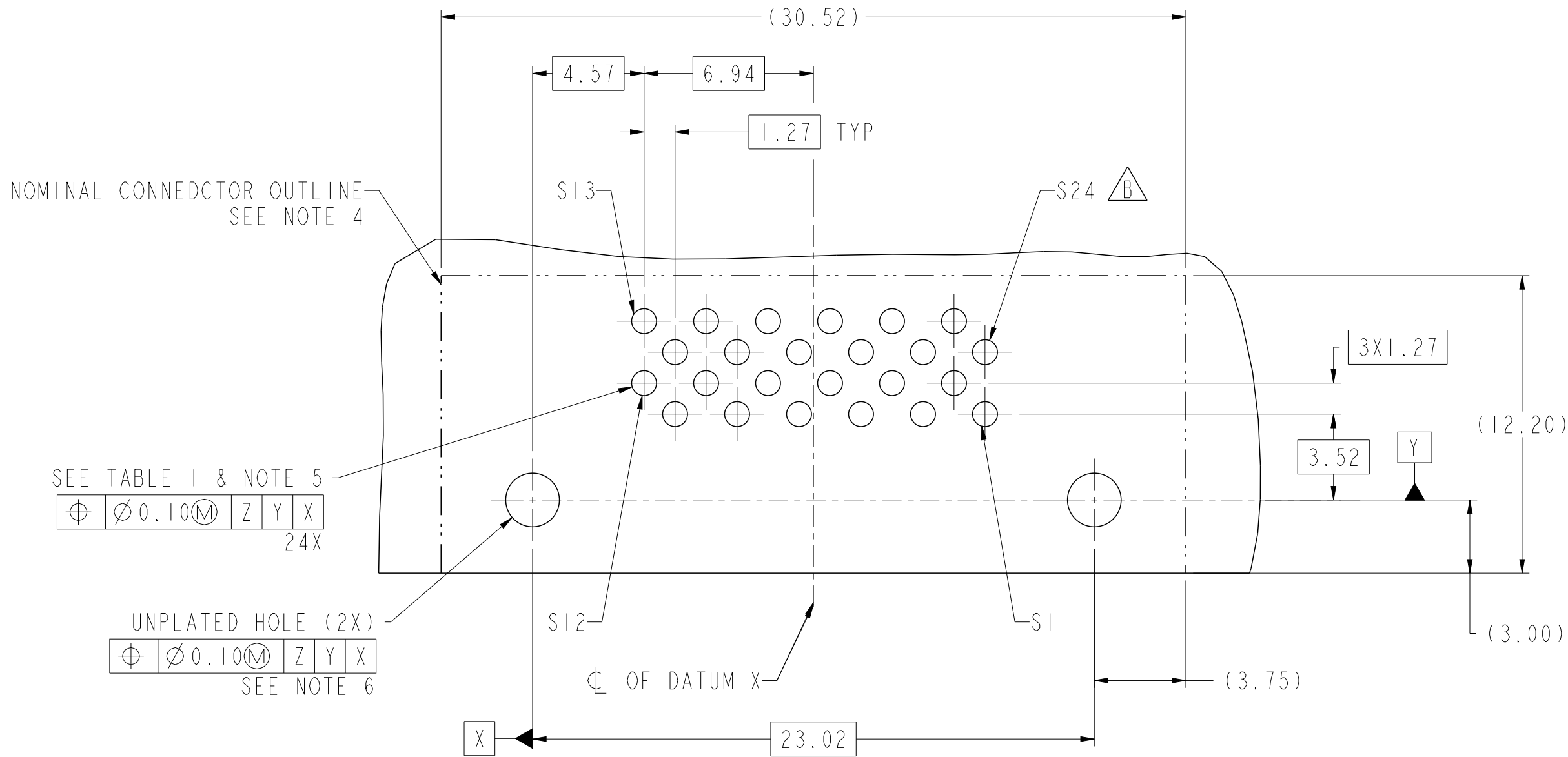
B

SIGNAL CONTACT												
PIN NUMBER	S13	S14	S15	S16	S17	S18	S19	S20	S21	S22	S23	S24
MATING LENGTH	S	S	L	L	L	L	L	L	L	L	L	S
PIN NUMBER	S12	S11	S10	S9	S8	S7	S6	S5	S4	S3	S2	S1
MATING LENGTH	S	S	L	S	S	L	S	S	L	L	L	S
"L": Long mating contact and "S": Short mating contact												



spec ref			dr		Leborn Luo		2017/09/10		projection		mm		size		A2		scale		5:1			
tolerance std			eng		Leborn Luo		2018/03/12						ecn no		ELX-DG-29419-1							
ISO 406			chr		Feng Zheng		2018/03/13						rel level		Released							
ISO 1101			appr		Pei-Ming Zheng		2018/03/13		product family													
surface			linear				title		HPCE BTB RA HEADER		dwg no		10145457		rev		B					
																			0.X		±0.5	
																			0.XX		±0.25	
			0.XXX																±0.10			
ISO 1302			angular		0°		±2°		cat. no.		Product - Customer Drw		sheet 1 of 3									

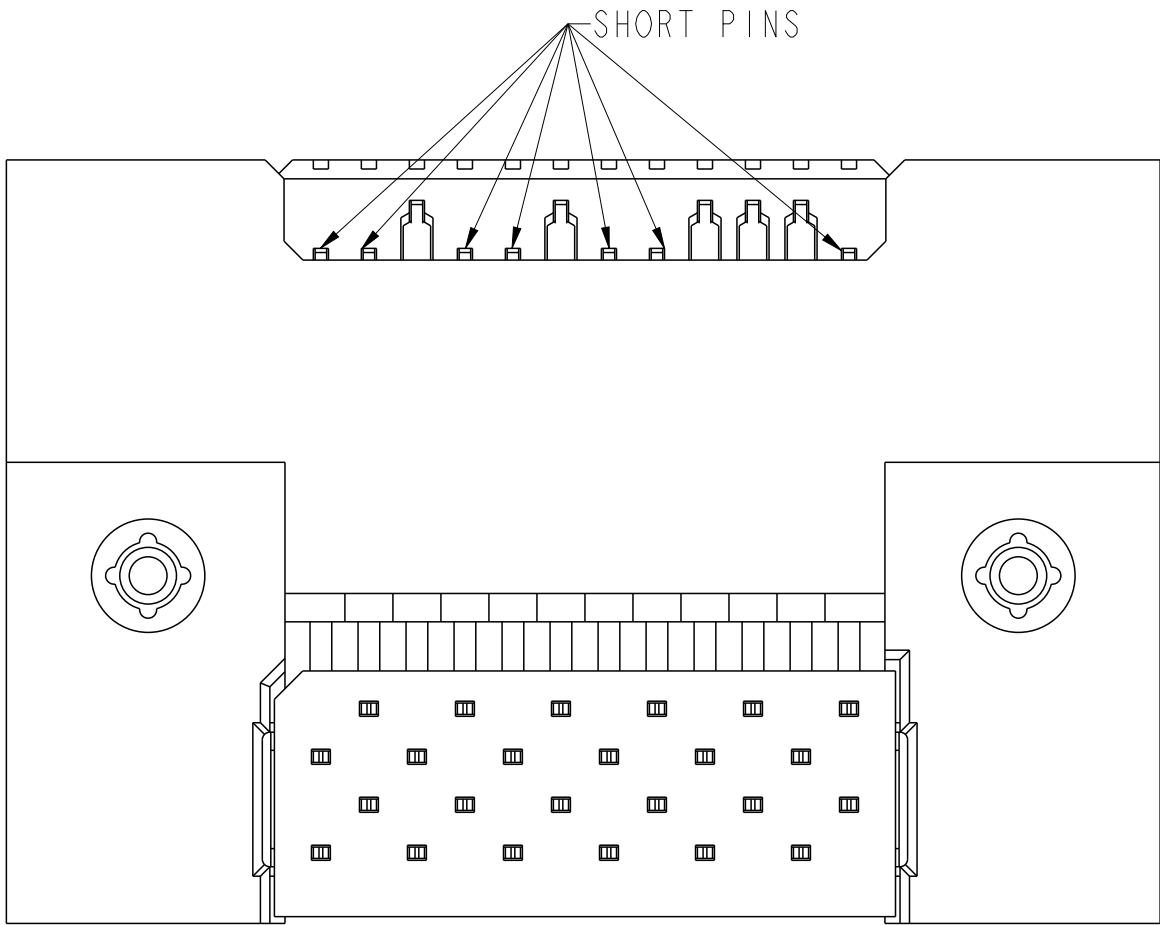
CONTACT TYPE	TOP LAYER DESCRIPTION	TABLE 1 (HPCE / SOLDER TAILS) PLATED THROUGH-HOLE REQUIREMENTS				
		DRILLED HOLE DIAMETER	COPPER THICKNESS	TIN-LEAD THICKNESS	TIN THICKNESS	FINISHED HOLE DIAMETER
SIGNAL	TIN-LEAD	1.10-1.16 (1.15 DRILL)	0.025 - 0.050	0.005 - 0.015	--	0.94 - 1.10
	IMMERSION TIN	1.10-1.16 (1.15 DRILL)	0.025 - 0.050	--	0.9 - 1.5um	0.94 - 1.10
	COPPER	1.10-1.16 (1.15 DRILL)	0.025 - 0.050	--	--	0.94 - 1.10



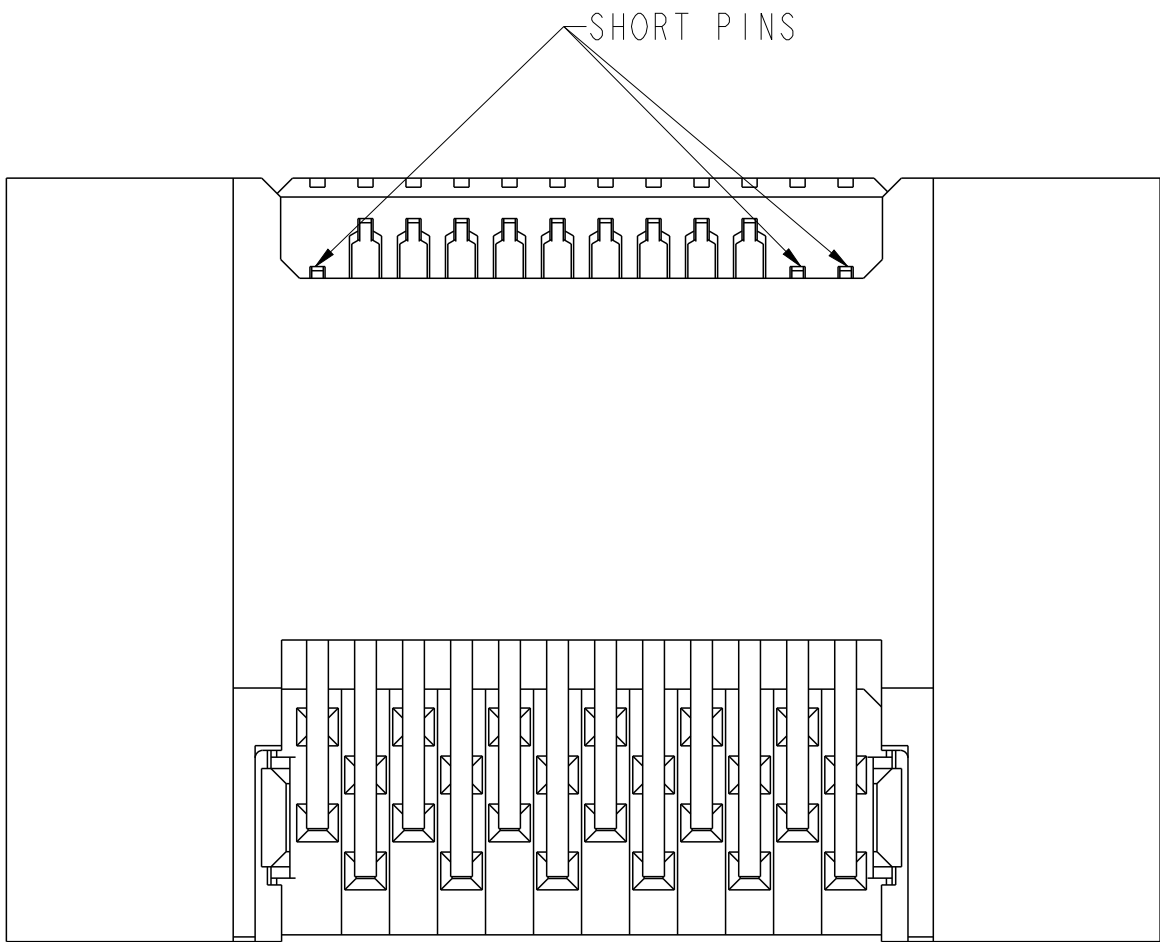
RECOMMENDED PCB LAYOUT
DIMENSION TOLERANCE IS $\pm 0.05\text{MM}$

spec ref		dr		Leborn Luo		2017/09/10		projection		mm		size		A2		scale		5:1			
tolerance std		eng		Leborn Luo		2018/03/12						ecn no		ELX-DG-29419-1		rel level		Released			
ISO 406		chr		Feng Zheng		2018/03/13															
ISO 1101		appr		Pei-Ming Zheng		2018/03/13															
								product family													
surface		linear		0.X		±0.5		Amphenol FCI		title		HPCE BTB RA HEADER		dwg no		10145457		rev		B	
				0.XX		±0.25															
				0.XXX		±0.10															
ISO 1302		angular		0°		±2°															

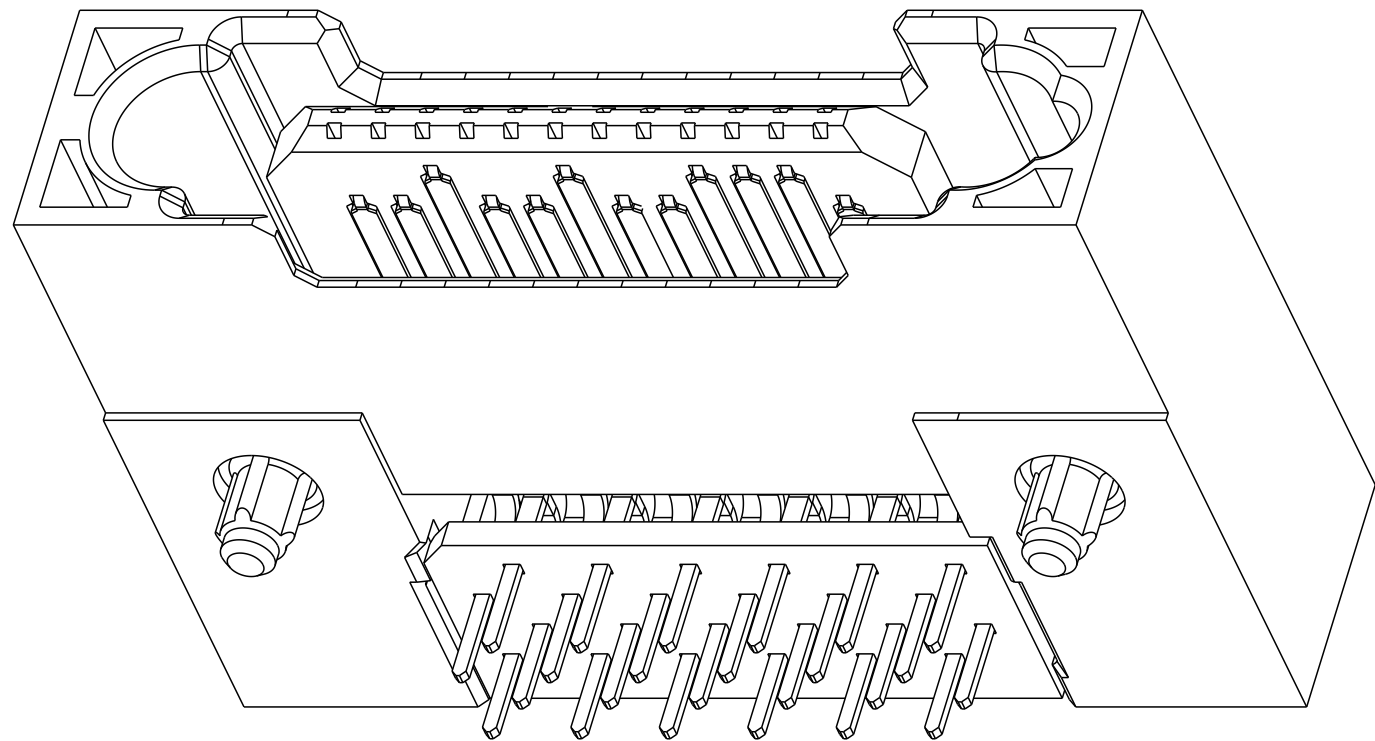
HPCE BTB PART NUMBER (TABLE 2)		
PART NUMBER	DIM" T" RECOMENDED BOARD THICKNESS	APPLICATION TYPE
10145457-001LF	1.57±0.13	STB



BOTTOM VIEW



TOP VIEW



NOTES:

- ① PRODUCT MARK:
PART NUMBER AND DATE CODE TO BE MARKED ON THIS SURFACE .
THE MARK CAN BE OMITTED IF THERE IS NOT ENOUGH SPACE ON THIS SURFACE.
2. MATERIALS:
-HOUSING : HIGH TEMPERATURE THERMOPLASTIC WITH GLASS FIBER, UL94V-0, BLACK.
-CONTACT : COPPER ALLOY.
3. CONTACT FINISH REF: GS-12-1031 SECTION 5.2.
- ④ DENOTES CONNECTOR KEEP OUT ZONE.
- ⑤ ALL HOLE DIAMETERS ARE FINISHED HOLE SIZES.
- ⑥ MOUNTING HOLES ARE UNPLATED
Ø2.18 +/- 0.03 FOR SOLDER TAILS
7. THE HOUSING COMPONENT WILL WITHSTAND EXPOSURE TO 245°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE APPLICATION.
8. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004.
9. PRODUCT SPECIFICATION : GS-12-1125.
APPLICATION SPECIFICATION : GS-20-0388.
PACKAGING SPECIFICATION: GS-14-2272.

spec ref		dr		Leborn Luo		2017/09/10		projection		mm		size		A2		scale		5:1	
tolerance std		eng		Leborn Luo		2018/03/12						ecn no		ELX-DG-29419-1		rel level		Released	
ISO 406		chr		Feng Zheng		2018/03/13													
ISO 1101		appr		Pei-Ming Zheng		2018/03/13													
surface		TOLERANCES UNLESS OTHERWISE SPECIFIED		Amphenol FCI		title		HPCE BTB RA HEADER		dwg no		10145457		rev		B			
ISO 1302		linear		0.X		±0.5		24S(10 short pins and 2.5mm pegs)											
				0.XX		±0.25													
				0.XXX		±0.10													
		angular		0°		±2°													
						cat. no.		Product - Customer Drw				sheet 3 of 3							